

## Dual N-Channel 20-V (D-S) MOSFET

| PRODUCT SUMMARY |                           |           |
|-----------------|---------------------------|-----------|
| $V_{DS}$ (V)    | $r_{DS(on)}$ ( $\Omega$ ) | $I_D$ (A) |
| 20              | 0.030 at $V_{GS} = 4.5$ V | 7.7       |
|                 | 0.036 at $V_{GS} = 2.5$ V | 7.0       |
|                 | 0.045 at $V_{GS} = 1.8$ V | 6.3       |

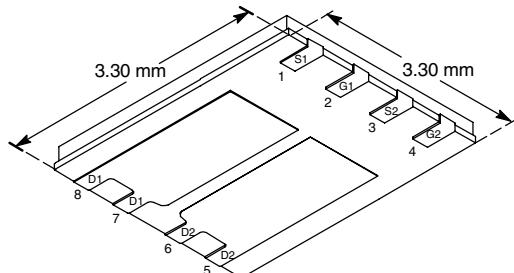
### FEATURES

- TrenchFET® Power MOSFETs: 1.8-V Rated
- New Low Thermal Resistance PowerPAK® Package with Low 1.07-mm Profile

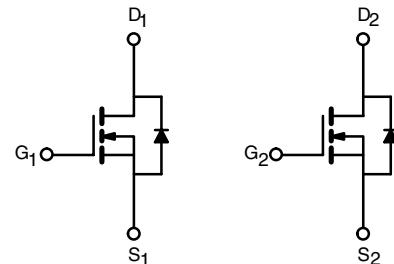

**RoHS\***  
COMPLIANT

### APPLICATIONS

- HDD Spindle Drive

**PowerPAK 1212-8**


Bottom View



N-Channel MOSFET

N-Channel MOSFET

**Ordering Information:** Si7904DN-T1  
Si7904DN-T1-E3 (Lead (Pb)-free)

| ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted |                |             |              |      |
|----------------------------------------------------------------|----------------|-------------|--------------|------|
| Parameter                                                      | Symbol         | 10 secs     | Steady State | Unit |
| Drain-Source Voltage                                           | $V_{DS}$       | 20          |              | V    |
| Gate-Source Voltage                                            | $V_{GS}$       | $\pm 8$     |              |      |
| Continuous Drain Current ( $T_J = 150$ °C) <sup>a</sup>        | $I_D$          | 7.7         | 5.3          | A    |
|                                                                |                | 5.5         | 3.8          |      |
| Pulsed Drain Current                                           | $I_{DM}$       | 20          |              |      |
| Continuous Source Current (Diode Conduction) <sup>a</sup>      | $I_S$          | 2.3         | 1.1          |      |
| Single Pulse Avalanche Current                                 | $I_{AS}$       | 15          |              |      |
| Avalanche Energy                                               | $E_{AS}$       | 11          |              | mJ   |
| Maximum Power Dissipation <sup>a</sup>                         | $P_D$          | 2.8         | 1.3          | W    |
|                                                                |                | 1.5         | 0.85         |      |
| Operating Junction and Storage Temperature Range               | $T_J, T_{stg}$ | - 55 to 150 |              | °C   |
| Soldering Recommendations <sup>b,c</sup>                       |                | 260         |              |      |

| THERMAL RESISTANCE RATINGS               |                 |            |         |      |
|------------------------------------------|-----------------|------------|---------|------|
| Parameter                                | Symbol          | Typical    | Maximum | Unit |
| Maximum Junction-to-Ambient <sup>a</sup> | $t \leq 10$ sec | $R_{thJA}$ | 35      | °C/W |
|                                          | Steady State    |            | 75      |      |
| Maximum Junction-to-Case                 | Steady State    | $R_{thJC}$ | 4       | 5    |

## Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (<http://www.vishay.com/ppg?73257>). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

**SPECIFICATIONS**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

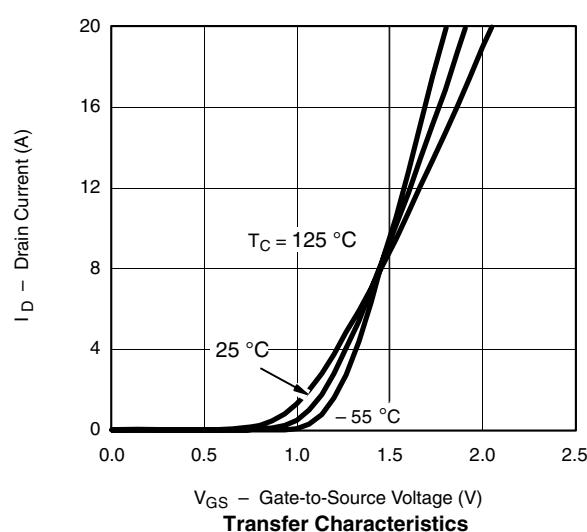
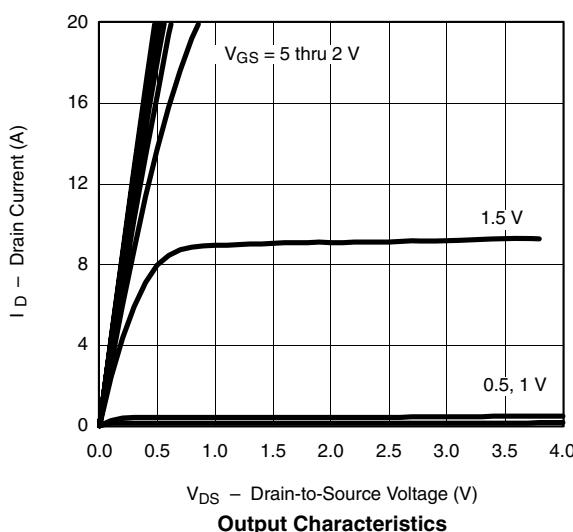
| Parameter                                     | Symbol              | Test Conditions                                                                                                      | Min  | Typ   | Max           | Unit     |
|-----------------------------------------------|---------------------|----------------------------------------------------------------------------------------------------------------------|------|-------|---------------|----------|
| <b>Static</b>                                 |                     |                                                                                                                      |      |       |               |          |
| Gate Threshold Voltage                        | $V_{GS(\text{th})}$ | $V_{DS} = V_{GS}$ , $I_D = 935 \mu\text{A}$                                                                          | 0.45 |       | 1.0           | V        |
| Gate-Body Leakage                             | $I_{GSS}$           | $V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 8 \text{ V}$                                                                  |      |       | $\pm 100$     | nA       |
| Zero Gate Voltage Drain Current               | $I_{DSS}$           | $V_{DS} = 20 \text{ V}$ , $V_{GS} = 0 \text{ V}$                                                                     |      | 1     | $\mu\text{A}$ |          |
|                                               |                     | $V_{DS} = 20 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 85^\circ\text{C}$                                          |      | 5     |               |          |
| On-State Drain Current <sup>a</sup>           | $I_{D(\text{on})}$  | $V_{DS} \geq 5 \text{ V}$ , $V_{GS} = 4.5 \text{ V}$                                                                 | 20   |       |               | A        |
| Drain-Source On-State Resistance <sup>a</sup> | $r_{DS(\text{on})}$ | $V_{GS} = 4.5 \text{ V}$ , $I_D = 7.7 \text{ A}$                                                                     |      | 0.025 | 0.030         | $\Omega$ |
|                                               |                     | $V_{GS} = 2.5 \text{ V}$ , $I_D = 7.0 \text{ A}$                                                                     |      | 0.030 | 0.036         |          |
|                                               |                     | $V_{GS} = 1.8 \text{ V}$ , $I_D = 1 \text{ A}$                                                                       |      | 0.037 | 0.045         |          |
| Forward Transconductance <sup>a</sup>         | $g_{fs}$            | $V_{DS} = 10 \text{ V}$ , $I_D = 7.7 \text{ A}$                                                                      |      | 23    |               | S        |
| Diode Forward Voltage <sup>a</sup>            | $V_{SD}$            | $I_S = 2.3 \text{ A}$ , $V_{GS} = 0 \text{ V}$                                                                       |      | 0.70  | 1.2           | V        |
| <b>Dynamic<sup>b</sup></b>                    |                     |                                                                                                                      |      |       |               |          |
| Total Gate Charge                             | $Q_g$               | $V_{DS} = 10 \text{ V}$ , $V_{GS} = 4.5 \text{ V}$ , $I_D = 7.7 \text{ A}$                                           |      | 10.2  | 15            | nC       |
| Gate-Source Charge                            | $Q_{gs}$            |                                                                                                                      |      | 1.3   |               |          |
| Gate-Drain Charge                             | $Q_{gd}$            |                                                                                                                      |      | 2.4   |               |          |
| Turn-On Delay Time                            | $t_{d(\text{on})}$  | $V_{DD} = 10 \text{ V}$ , $R_L = 10 \Omega$<br>$I_D \geq 1 \text{ A}$ , $V_{GEN} = 4.5 \text{ V}$ , $R_G = 6 \Omega$ |      | 15    | 23            | ns       |
| Rise Time                                     | $t_r$               |                                                                                                                      |      | 50    | 75            |          |
| Turn-Off Delay Time                           | $t_{d(\text{off})}$ |                                                                                                                      |      | 60    | 90            |          |
| Fall Time                                     | $t_f$               |                                                                                                                      |      | 45    | 68            |          |
| Source-Drain Reverse Recovery Time            | $t_{rr}$            | $I_F = 2.3 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$                                                          |      | 40    | 80            |          |

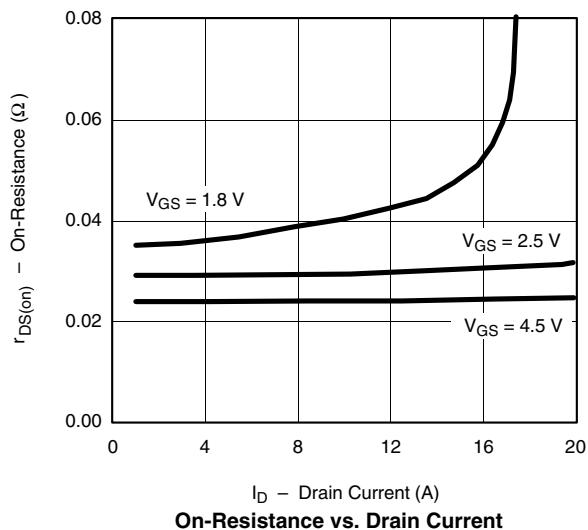
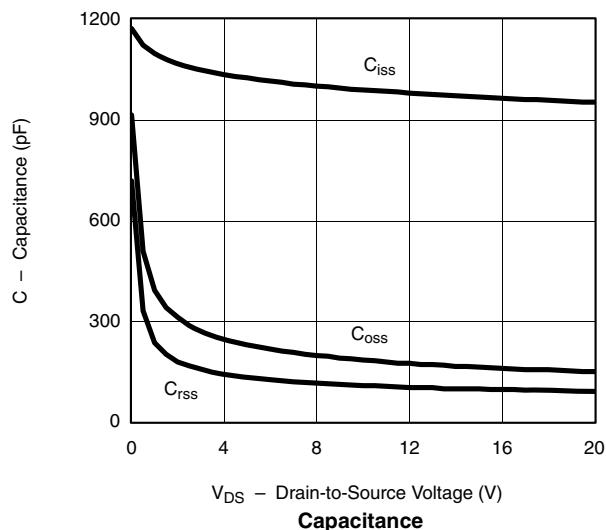
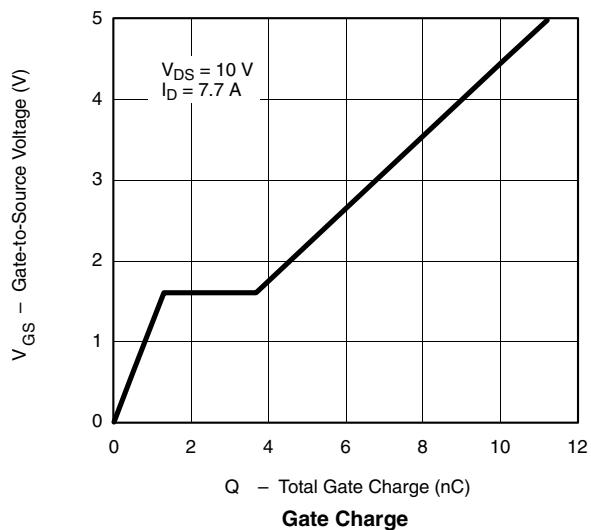
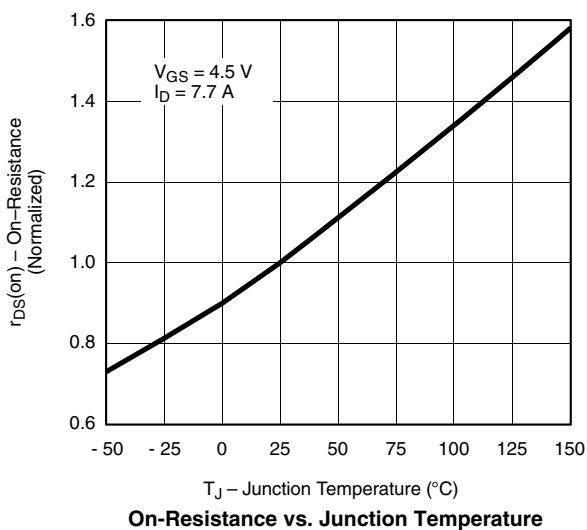
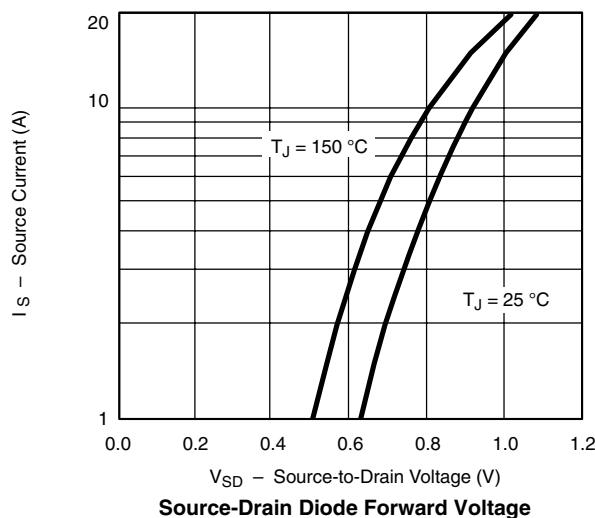
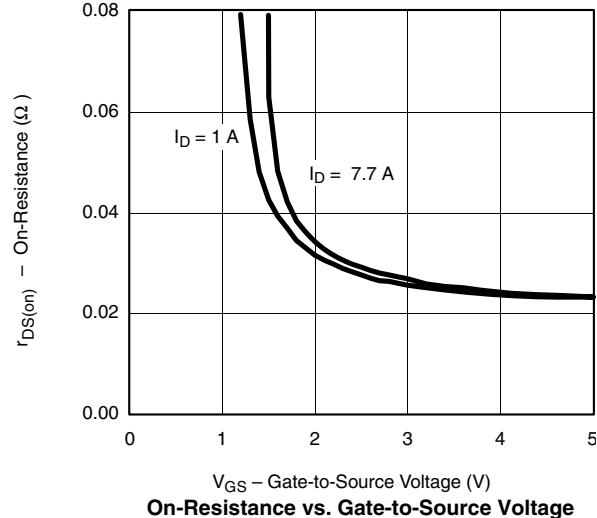
## Notes

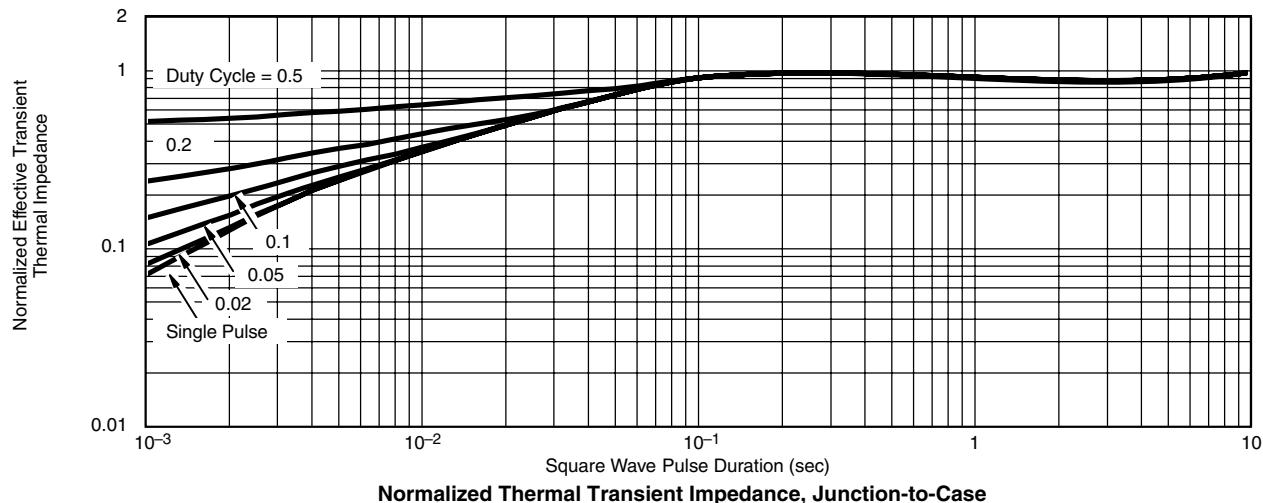
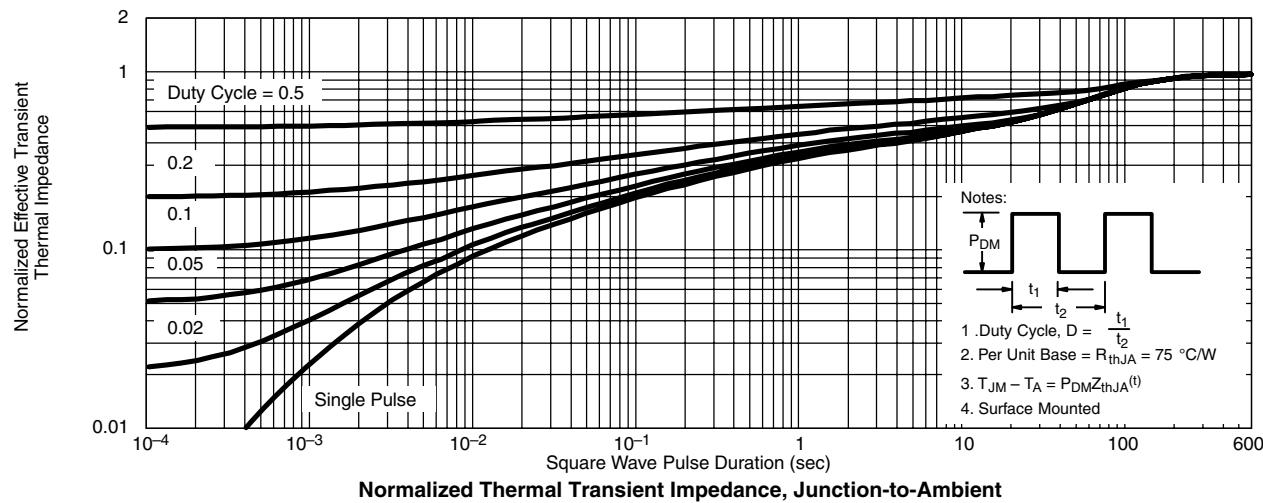
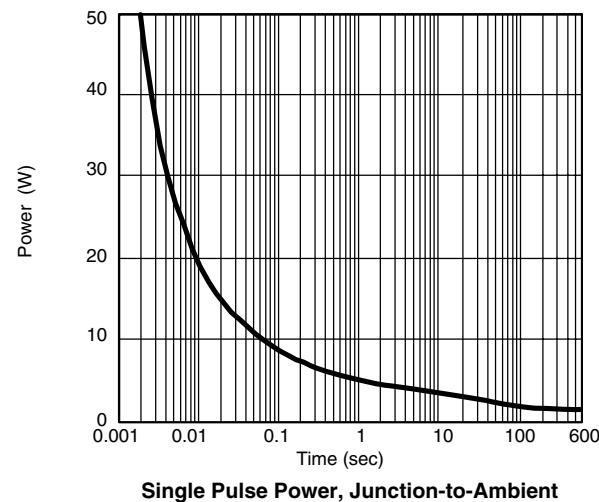
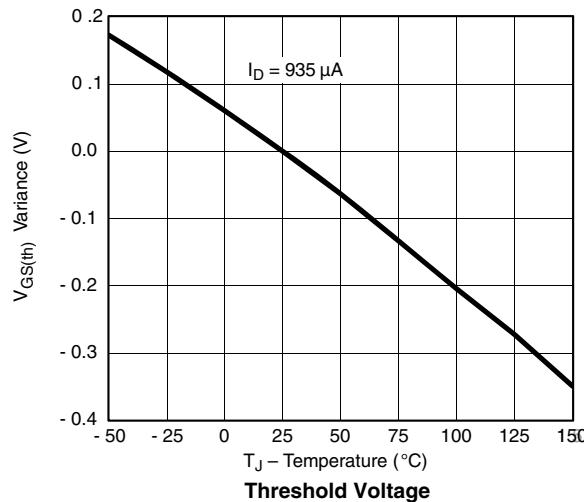
a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS**  $T_A = 25^\circ\text{C}$ , unless otherwise noted


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**On-Resistance vs. Drain Current**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**

**Source-Drain Diode Forward Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

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